


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HNSR*Z25Q81Q	A	ZA41	2017-11-22
Amount	UoM	Unit type	ST ECOPACK Grade	
70	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SMC	4.3-2.77-2	2	J bend	
Comment	Package: SMA. MDF valid for CPs: STPS2L30A - STPS1L30A - 100393426			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 7th July 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	171
Lead	2.64	Soft solder	37643

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HNSR*ZZ5Q81Q					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.279	mg	supplier	die	Silicon (Si)	7440-21-3		1.086	mg	849101	15514
				supplier	metallization	Aluminium (Al)	7429-90-5		0.045	mg	35184	643
				supplier	passivation	Nickel (Ni)	7440-02-0		0.005	mg	3909	71
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	781	14
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1564	29
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	5473	100
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	782	14
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1564	29
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	5473	100
				supplier	polymer die coating	Durimide	Proprietary		0.123	mg	96169	1757
Leadframe & clip	M-004 Copper and its alloys	26.861	mg	supplier	alloy	Copper (Cu)	7440-50-8		26.848	mg	999516	383543
				supplier	alloy	Zinc (Zn)	7440-66-6		0.001	mg	37	14
				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	112	43
				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		0.009	mg	335	129
Soft solder	Solder	2.849	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.635	mg	924886	37643
				supplier	solder	Tin (Sn)	7440-31-5		0.143	mg	50193	2043
				supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	24921	1014
encapsulation	M-011 Other inorganic materials	38.370	mg	supplier	mold compound	Amorphous silica	7631-86-9		26.352	mg	686787	376457
				supplier	mold compound	Quartz	14808-60-7		9.600	mg	250195	137143
				supplier	mold compound	Phenol resin	9003-35-4		2.303	mg	60021	32900
				supplier	mold compound	carbon black	1333-86-4		0.115	mg	2997	1643
connections coating	Solder	0.641	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.641	mg	1000000	9157